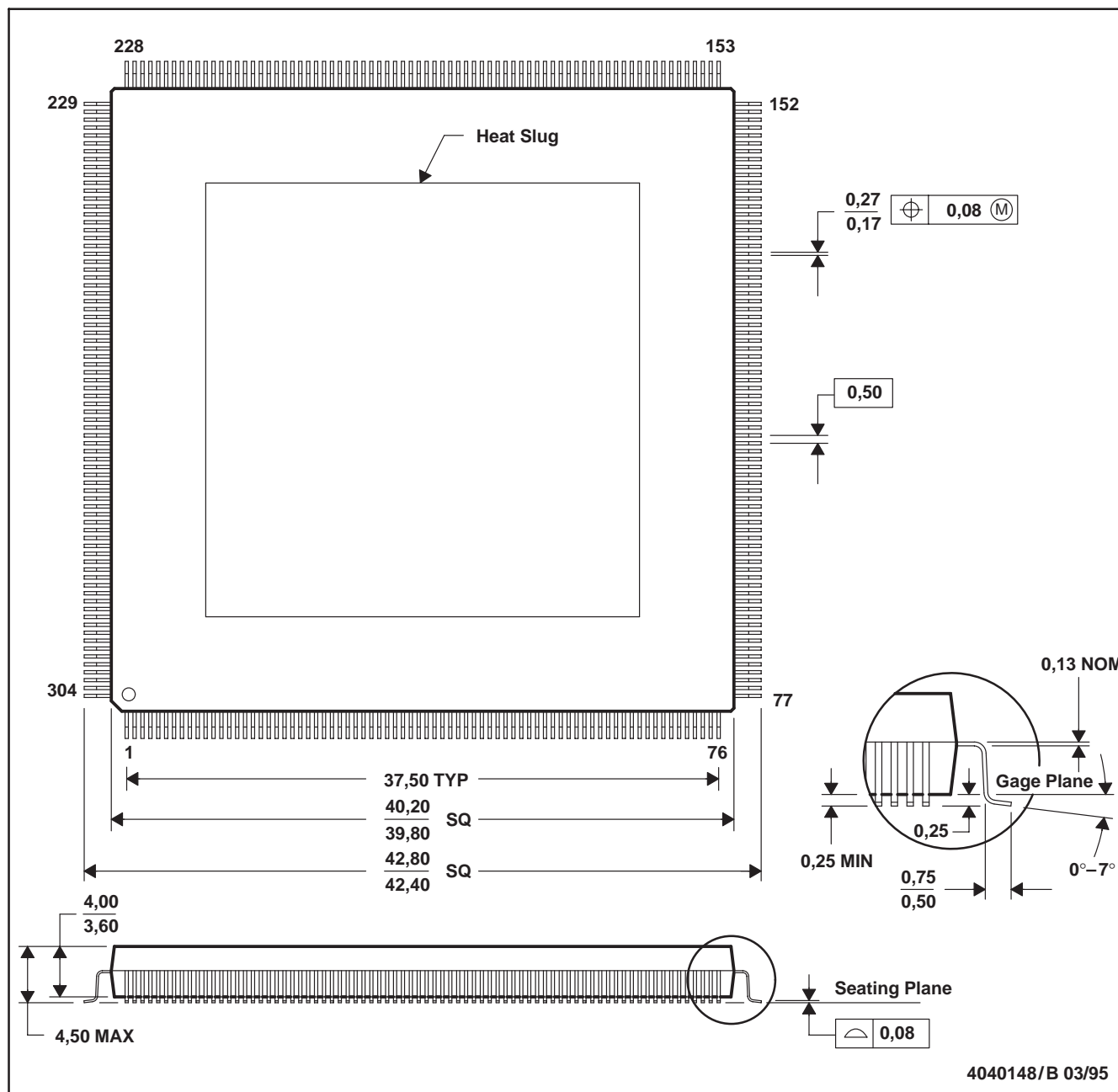


## PDB (S-PQFP-G304)

## PLASTIC QUAD FLATPACK (DIE-DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced molded plastic package with a heat slug (HSL)
  - D. Falls within JEDEC MO-143

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